

techman / October 26, 2010 09:46AM

[\[Sci-tech Policy\] MoEA Approved HP's and IMEC's Applications to Set R&D Centers in Taiwan: the Number of Foreign Investors to Set R&D Centers in Taiwan in 2010 May Reach 14](#)

[Sci-tech Policy] MoEA Approved HP's and IMEC's Applications to Set R&D Centers in Taiwan; the Number of Foreign Investors to Set R&D Centers in Taiwan in 2010 May Reach 14 ([Chinese Version](#))

Udn.com (2010/10/22) Ministry of Economic Affairs (MoEA) announced on 21 that the number of foreign investors to establish research and development (R&D) centers in Taiwan may reach 14 this year with a total investment of 432 million U.S. dollars, which has made the highest record in recent years. Beside of Microsoft, Hewlett-Packard (HP), etc., whose establishments of R&D centers in Taiwan have been determined, the current foreign investors about to establish R&D centers in Taiwan by the end of the year have included Elpida from Japan and Corning from the U.S.

MoEA approved the R&D center establishment applications filed by Hewlett-Packard (HP) and Interuniversity Microelectronics Centre (IMEC) on October 21. HP planned to invest 3.6 billion NT dollars to build in Taiwan its global integration and R&D center for information techniques; IMEC planned to invest 150 million NT dollars on an interdisciplinary-cooperation center for micro-electronics, medical electronics, green energy, etc.

MoEA pointed out, owing to the realization of the cross-strait Economic Cooperation Framework Agreement (ECFA), many foreign investors believed that the cross-strait relation would become more peaceful and steadier than before so that they would like to move the R&D of their advanced process sections in Taiwan.

These establishments of R&D centers were realized under the MoEA incentive program to encourage foreign high-tech companies to set up research footholds in Taiwan, which came into force in 2002. Six foreign companies established R&D centers in Taiwan under the program last year, including Sony, Dupont, Corning, Fujitsu, ASML, etc.; this year, MoEA received applications submitted by Microsoft, HP, IBM, IMEC, TEL, etc.

Presently, MoEA is in negotiation with Elpida on its establishment of R&D center in Taiwan, and the concrete determinations may be reached by the end of the year. Elpida plans to invest more than 100 million U.S. dollars in Taiwan, establishing a massive R&D center which demands for over 100 researchers on DRAM process under 40 nm.

The other remarkable application which may be approved by the end of the year is filed by the global glass substrate maker Corning. Corning plans to move the R&D of its advanced process section for iPhone touch panel in Taiwan.

#### Related Historical Messages:

[\[Industrial\]\[DRAM\] Ministry of Economic Affairs' Financial Support for R&D Centers in Taiwan Program Succeeds: Elpida Will Spend Three Billion NT Dollars Establishing R&D Center in Taiwan 2010/09/27](#)

[\[Cloud Computing\] Chunghwa Telecom and IBM Form Alliance on Cloud Computing 2010/09/27](#)

[\[International Cooperation\]\[Electronics Industry\] Canada's Major EMS Company Celestica Inc. to Establish R&D Center in Taiwan 2010/09/20](#)

[\[Sci-tech Policy\] Ministry of Economic Affairs Offers Financial Support to Microsoft's Cloud Computing Center 2010/07/19](#)

#### Reference:

[Udn.com 2010/10/22](#) (Chinese)

---

[National Science Council International Cooperation Sci-Tech Newsbrief](#)

---

Edited 2 time(s). Last edit at 10/26/2010 09:55AM by techman.

---